

# N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub>	30	V		
$R_{DS(on)} V_{GS} = 10 V$	2	mΩ		
$R_{DS(on)}$ $V_{GS} = 4.5 \text{ V}$	2.4	mΩ		
I <sub>D</sub>	110	Α		
Configuration	Single			

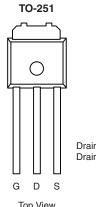
#### **FEATURES**

- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested
   Compliant to RoHS Directive 2011/65/EU





- OR-ing
- Server
- DC/DC



Drain Connected to Drain-Tab

Top	View

	D 0
G <b>o</b> -	
	<b>0</b> S
N-0	Channel MOSFET

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V <sub>DS</sub>	30	V
Gate-Source Voltage		V <sub>GS</sub>	± 20	
	T <sub>C</sub> = 25 °C		110 <sup>a, e</sup>	
Continuous Drain Current (T <sub>J</sub> = 175 °C)	T <sub>C</sub> = 70 °C		98 <sup>e</sup>	
Continuous Diain Current (1 <sub>J</sub> = 175 C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	35.8 <sup>b, c</sup>	A
	T <sub>A</sub> = 70 °C		27 <sup>b, c</sup>	^
Pulsed Drain Current		I <sub>DM</sub>	300	
Avalanche Current Pulse	L = 0.1 mH	I <sub>AS</sub>	39	
Single Pulse Avalanche Energy	L=0.1 IIII	E <sub>AS</sub>	94.8	mJ
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	I.	90 <sup>a, e</sup>	А
	T <sub>A</sub> = 25 °C	I <sub>S</sub>	3.13 <sup>b, c</sup>	
Maximum Power Dissipation	T <sub>C</sub> = 25 °C		250 <sup>a</sup>	
	T <sub>C</sub> = 70 °C	P <sub>D</sub>	175	w
	T <sub>A</sub> = 25 °C	r <sub>D</sub>	3.75 <sup>b, c</sup>	
	T <sub>A</sub> = 70 °C		2.63 <sup>b, c</sup>	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Тур.	Max.	Unit
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 10 sec	R <sub>thJA</sub>	32	40	°C/W
Maximum Junction-to-Case	Steady State	R <sub>thJC</sub>	0.5	0.6	C/ VV

- a. Based on T<sub>C</sub> = 25 °C. b. Surface mounted on 1" x 1" FR4 board.

- b. Surface motived of 1. X.1.1144 board.
  c. t = 10 sec.
  d. Maximum under steady state conditions is 90 °C/W.
  e. Calculated based on maximum junction temperature. Package limitation current is 90 A.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						_
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30			V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 250 \		35		>//00
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_{D} = 250  \mu A$		- 7.5		mV/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.5		2.5	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zana Oata Waltana Basis Oursest		V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V			1	^
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			10	μA
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	90			Α
		$V_{GS} = 10 \text{ V}, I_D = 38.8 \text{ A}$		2		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 37 \text{ A}$		2.4		mΩ
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_{D} = 38.8 \text{ A}$		160		S
Dynamic <sup>b</sup>						•
Input Capacitance	C <sub>iss</sub>			6201		
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		1725		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			970		1
Total Gate Charge	0	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 38.8 \text{ A}$		171		nC
Total Gate Charge	$Q_g$			81.5		
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 28.8 \text{ A}$		34		
Gate-Drain Charge	$Q_{gd}$			29		
Gate Resistance	R <sub>g</sub>	f = 1 MHz		1.4	2.1	Ω
Turn-On Delay Time	t <sub>d(on)</sub>			18	27	
Rise Time	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, R_{L} = 0.625 \Omega$		11	17	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D\cong 24$ A, $V_{GEN}=10$ V, $R_g=1$ $\Omega$		70	105	
Fall Time	t <sub>f</sub>			10	15	
Turn-On Delay Time	t <sub>d(on)</sub>			55	83	ns
Rise Time	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_L$ = 0.67 $\Omega$		180	270	1
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D\cong 22.5$ A, $V_{GEN}$ = 4.5 V, $R_g$ = 1 $\Omega$		55	83	
Fall Time	t <sub>f</sub>			12	18	1
<b>Drain-Source Body Diode Characteristic</b>	cs					
Continuous Source-Drain Diode Current	I <sub>S</sub>	$T_C = 25  ^{\circ}C$			120	Α
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				120	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = 22 A		0.8	1.2	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>			52	78	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	L_ = 20 A di/dt = 100 A/vo T = 25 °C		70.2	105	nC
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		27		
Reverse Recovery Rise Time	t <sub>b</sub>			25		ns

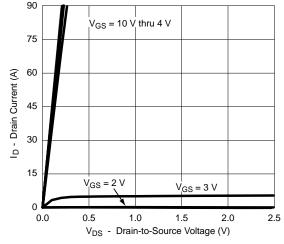
#### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

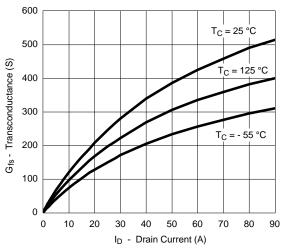
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



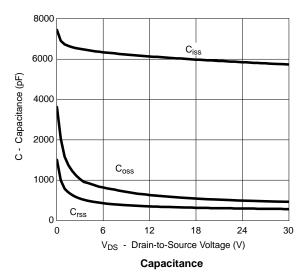
#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

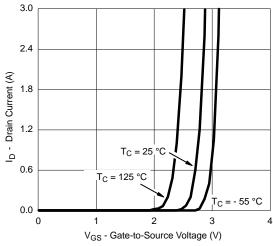


#### **Output Characteristics**

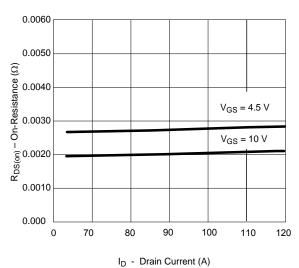


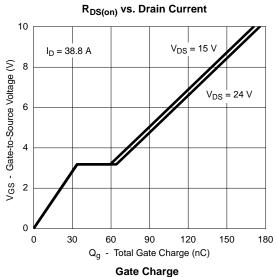
#### **Transconductance**





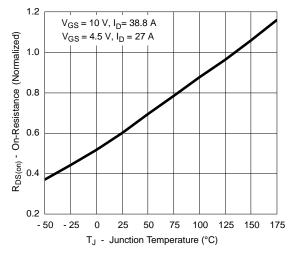
**Transfer Characteristics** 



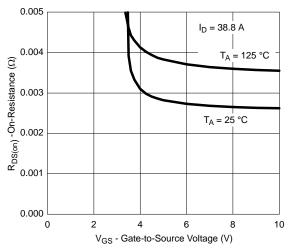




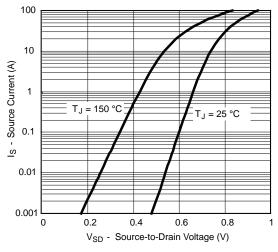
#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



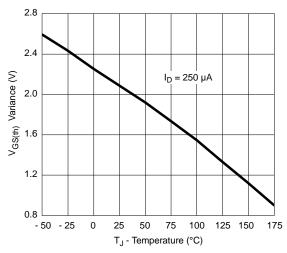
On-Resistance vs. Junction Temperature



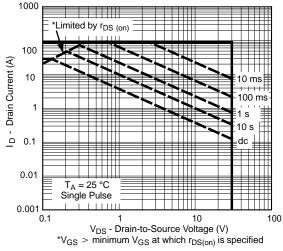
 $R_{DS(on)}$  vs.  $V_{GS}$  vs. Temperature



Forward Diode Voltage vs. Temperature



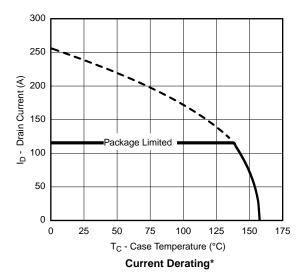
Threshold Voltage

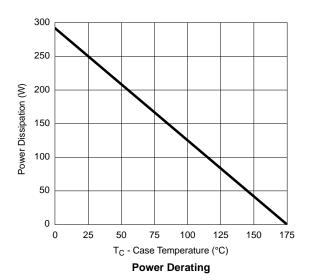


Safe Operating Area, Junction-to-Ambient

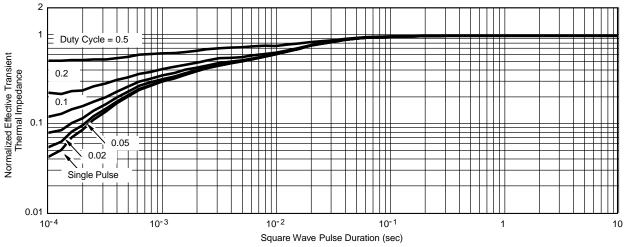


#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





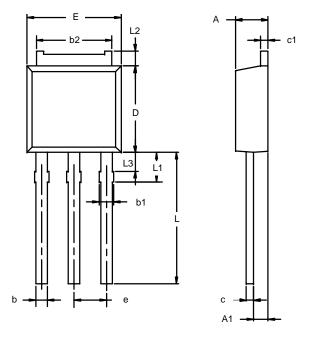
\*The power dissipation  $P_D$  is based on  $T_{J(max)}$  = 175 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



Normalized Thermal Transient Impedance, Junction-to-Case



### **TO-251AA**



Note: Dimension L3 is for reference only
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	MILLIM	IETERS	INC	HES
Dim	Min	Max	Min	Max
Α	2.21	2.38	0.087	0.094
<b>A</b> 1	0.89	1.14	0.035	0.045
b	0.71	0.89	0.028	0.035
b1	0.76	1.14	0.030	0.045
b2	5.23	5.43	0.206	0.214
С	0.46	0.58	0.018	0.023
с1	0.46	0.58	0.018	0.023
D	5.97	6.22	0.235	0.245
Е	6.48	6.73	0.255	0.265
е	2.28 BSC		0.090	BSC
L	3.89	9.53	0.153	0.375
L1	1.91	2.28	0.075	0.090
L2	0.89	1.27	0.035	0.050
L3	1.15	1.52	0.045	0.060



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